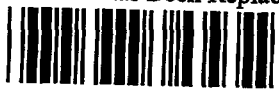
ELECTRICALLY CONDUCTIVE PASTE MATERIALS AND APPLICATIONS

ABSTRACT

A structure and method of fabrication are described. The structure is a combination of a polymeric material (36) and particles (32), e.g. Cu, having an electrically conductive coating (34), e.g. Sn. Heat is applied to fuse the coating of adjacent particles (32). The polymeric material (36) is a thermoplastic. The structure is disposed between two electrically conductive surfaces (40,42), e.g. chip and substrate pads, to provide electrical interconnection and adhesion between their pads.

Fig. 4.

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